



# **Application note**

# DA14580 Resolvable private address guidelines

**AN-B-022** 

# **Abstract**

Bluetooth Low Energy devices are identified using a device address. Device addresses may be either a public device address or a random device address. A device with a random resolvable private address can be identified by bonded peers in subsequent advertising or connection sessions even when it uses a different address. Guidelines and methods of implementing devices using and resolving resolvable private addresses are described in this document.



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Figure 1: Message flow during bonding procedure ...... Error! Bookmark not defined.



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# 1 Terms and definitions

IRK Identity Resolving Key

LTK Long Term Key

MSB Most Significant Bits

MITM Man In The Middle

# 2 References

- 1. Bluetooth Specification version 4.0
- 2. RW-BLE-GAP-IS, GAP Interface Specification, Riviera Waves

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# 3 Introduction

This document describes the procedures that must be followed by a DA14580 host application in order to:

- Configure its local device address as a resolvable private address.
- Identify a bonded peer device using a resolvable private address in subsequent scanning or connection operations.

# 4 Random resolvable address mode

# 4.1 Set up device configuration

A resolvable private address is generated from an Identity Resolving Key (IRK). The IRK must be generated by the host application and provided to the BLE stack in the corresponding field of a GAPM\_SET\_DEV\_CONFIG\_CMD message.

If the device role is set to peripheral role (GAP\_PERIPHERAL\_SLV), the privacy bit in the flag field (GAPM\_CFG\_PRIVACY\_EN) must be set.

# 4.2 Advertising

In order to use a resolvable random address during advertising, the host application must set *op.addr\_src* to GAPM\_GEN\_RSLV\_ADDR in the GAPM\_START\_ADVERTISE\_CMD command. Field *op.renew\_dur* controls the duration of the resolvable address before it gets regenerated and it is counted in units of 10 ms. Minimum valid value for *renew\_dur* is 15000 (150 s). If the value of *renew\_dur* is < 15000, the BLE stack will automatically set it to 15000.

The BLE stack will send a GAPM\_DEV\_BDADDR\_IND event containing the generated random resolvable address to the host application upon receiving the GAPM\_START\_ADVERTISE\_CMD command and each time a new resolvable random address is generated. The host application may store the generated random address for future usage. The random address generation process is active until the GAPM\_START\_ADVERTISE\_CMD command is completed, i.e. until a peer connects to the device or the host application cancels advertising with a GAPM\_CANCEL\_CMD command.

A GAPM\_START\_ADVERTISE\_CMD command with *op.addr\_src* = GAPM\_GEN\_RSLV\_ADDR always starts by generating a new resolvable random address. If a host application has a stored address and wishes to reuse the last generated resolvable random address in subsequent advertising commands, it can set the *op.addr\_src* field to GAPM\_PROVIDED\_RND\_ADDR and copy the stored address in *op.addr* to force the BLE stack to use this address.

# 4.3 Scan/connection

Similar to the advertising procedure, the host application in central role devices can set *op.addr\_src* to GAPM\_GEN\_RSLV\_ADDR in commands GAPM\_START\_SCAN\_CMD and GAPM\_START\_CONNECTION\_CMD to enable random resolvable private addressing. The address is generated by the BLE stack and returned to the host application in a GAPM\_DEV\_BDADDR\_IND message.

The application can set *op.addr\_src* to GAPM\_PROVIDED\_RND\_ADDR in these two commands to reuse a previously generated random address.

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# 5 Bonding procedure

A device using a resolvable private address should be able to distribute its local IRK to peer devices during the bonding procedure. Otherwise it will not be possible for its peer devices to identify the device when it updates its resolvable private random address.

The bonding procedure must be initiated by the central device with a GAPC\_BOND\_CMD command.

# 5.1 IRK distribution from a central device perspective

The host application initiates the bonding procedure using a GAPC\_BOND\_CMD command with:

- Set GAP\_KDIST\_IDKEY bit of pairing.ikey\_dist to enable distribution of its own IRK
- Set GAP\_KDIST\_IDKEY bit of pairing.rkey\_dist in GAPC\_BOND\_CMD to request peer IRK distribution

During the bonding procedure the central host application will receive a GAPC\_BOND\_IND message with *info* = GAPC\_IRK\_EXCH containing the peer's IRK in *data.irk*.

# 5.2 IRK distribution from a peripheral device perspective

During the bonding procedure initiated by the peer central device, the host application of the peripheral device receives a GAPC\_BOND\_REQ\_IND with *request* = GAPC\_PAIRING\_REQ.

The application will respond with a GAPC\_BOND\_CFM with request = GAPC\_PAIRING\_RSP and

- Set GAP\_KDIST\_IDKEY bit of data.pairing.rkey\_dist to enable the distribution of its own IRK
- Set GAP\_KDIST\_IDKEY bit of data.pairing.ikey\_dist to request peer IRK distribution

The BLE stack will handle the distribution of the peripheral's IRK to the peer central device.

Later during the bonding procedure, the peripheral host application will receive a GAPC\_BOND\_IND message with *info* = GAPC\_IRK\_EXCH containing the peer's IRK in *data.irk*.

# 6 Resolving the address

A device can resolve a resolvable address by sending a GAPM\_RESOLV\_ADDR\_CMD command to TASK GAPM with the address to be resolved in *addr field* and the stored IRKs of bonded devices.

If the address is resolved by any of the provided IRKs, the TASK\_GAPM will respond with a GAPM\_ADDR\_SOLVED\_IND message containing the resolved address and the IRK resolving it. Otherwise, a GAPM\_CMP\_EVT event or GAPM\_RESOLV\_ADDR operation with status value GAP\_ERR\_NOT\_FOUND will be sent.

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# 7 Example

This section describes an example of a DA14580 device with a central role and a public address connecting to a DA14580 device with peripheral role and resolvable private random address. For better understanding of resolvable private address usage, the message flow of host applications running on both devices will be described for the following procedures:

- 1. Configure and start advertising with resolvable private address on peripheral device.
- 2. Bonding procedure.
- 3. Resolve peripheral device random address during scanning procedure.

# 7.1 Advertising with resolvable private address

The host application of the DA14580 in a peripheral role must generate the IRK before device configuration. This can be done in the *app\_init()* function. The following member is added in *app\_sec\_env* to store the IRK data. The IRK size always has the maximum value: KEY\_LEN = 16 (bytes).

```
struct gap sec key irk;
```

A sample function of pseudo random key generation is as follows:

```
void app_sec_gen_irk(void)
{
    // Counter
    uint8_t i;
    // Randomly generate the end of the LTK
    for (i = 0; i < KEY_LEN; i++)
    {
        app_sec_env.irk.key[i] = rand()%256;
    }
}</pre>
```

In a device configuration command, the application provides the stored local IRK and IRK size. It must also enable the peripheral privacy flag. Below follows a sample code with the required actions for this operation.

```
// set device configuration
struct gapm_set_dev_config_cmd* cmd = KE_MSG_ALLOC(GAPM_SET_DEV_CONFIG_CMD,
TASK_GAPM, TASK_APP, gapm_set_dev_config_cmd);
cmd->role = GAP_PERIPHERAL_SLV;
memcpy (cmd->irk.key, app_sec_env.irk.key, KEY_LEN);
cmd->flags = GAPM_CFG_PRIVACY_EN;
```

In a start advertising command, the application must set *addr\_src* to GAPM\_GEN\_RSLV\_ADDR. The *renew\_dur* field must be set to the required lifetime of the random address before it gets regenerated.

# 7.2 Bonding procedure

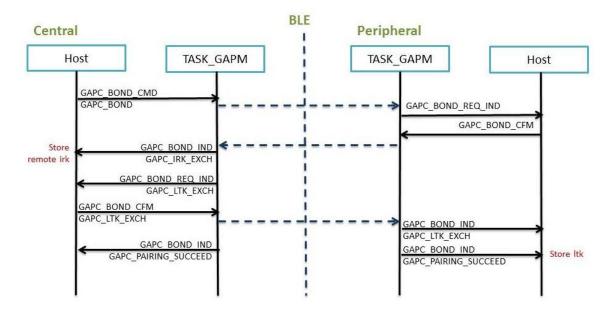


Figure 1: Message flow during bonding procedure

A central device can discover and connect to peripherals with a resolvable private address.

The central device can determine whether a discovered address is a resolvable random address by examining the combination of *adv\_addr\_type* in GAPM\_ADV\_REPORT\_IND or *peer\_addr\_type* in GAPC\_CONNECTION\_REQ\_IND with the value of the two most significant bits in the address. The address type of resolvable addresses is '0' for public addresses and '1' for random addresses. The two most significant bits of resolvable private addresses are equal to '01'.

For more details about resolvable private address format refer to [1], *Volume 3, 10.8.2.2 Resolvable Private Address Generation Procedure.* 

After establishing a connection, the host application in a central device must initiate the bonding procedure with a peripheral to obtain the remote IRK. The bonding procedure is initiated with a GAPM\_BOND\_CMD command.

Other security parameters (such as OOB data presence, MITM, LTK distributor) can have various values depending on the application requirements. For this example we will assume that MITM is disabled, OOB data are not present and the LTK distributor will be the security initiator (central).

Below is a sample code enabling this setup:

```
struct gapc_bond_cmd * req = KE_MSG_ALLOC (GAPC_BOND_CMD, KE_BUILD_ID(TASK_GAPC,
app_env.conidx), TASK_APP, gapc_bond_cmd);
req->operation = GAPC_BOND;
req->pairing.sec_req = GAP_NO_SEC;
// OOB information
req->pairing.oob = GAP_OOB_AUTH_DATA_NOT_PRESENT; // No_OOB_data_present
// IO capabilities
req->pairing.iocap = GAP_IO_CAP_NO_INPUT_NO_OUTPUT; // No_I/O_capabilities
// Authentication requirements
req->pairing.auth = GAP_AUTH_REQ_NO_MITM_BOND; //Bonding, No_MITM
// Encryption key size = 16;
```



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```
//Initiator key distribution
req->pairing.ikey_dist = SMP_KDIST_ENCKEY; //Initiator distributes LTK
//Responder key distribution
req->pairing.rkey dist = SMP_KDIST_IDKEY; //Request receiver to distribute IRK
```

The host application in the peripheral device will receive a GAPC\_BOND\_REQ\_IND message with request = GAPC\_PAIRING\_REQ, indicating that the central device has started the pairing (bonding) procedure. It must respond with a GAPC\_BOND\_CFM. Below is the sample code for the response:

```
struct gapc bond cfm* cfm = KE MSG ALLOC (GAPC BOND CFM, TASK GAPC, TASK APP,
gapc bond cfm);
cfm->request = GAPC PAIRING RSP; //pairing response
cfm->accept = true;
// OOB information
cfm->data.pairing feat.oob
                                      = GAP OOB AUTH DATA NOT PRESENT; // No OOB data
present
// Encryption key size
cfm->data.pairing feat.key size
                                      = KEY LEN;
// IO capabilities
cfm->data.pairing feat.iocap
                                      = GAP IO CAP NO INPUT NO OUTPUT; // No I/O
capabilities
// Authentication requirements
cfm->data.pairing feat.auth
                                      = GAP AUTH REQ NO MITM BOND; //Bonding, No MITM
//Security requirements
cfm->data.pairing feat.sec req
                                      = GAP NO SEC;
//Initiator key distribution
cfm->data.pairing feat.ikey dist
                                      = SMP KDIST ENCKEY; //Initiator distributes LTK
//Responder key distribution
cfm->data.pairing feat.rkey dist
                                      = SMP KDIST IDKEY; //Request receiver to
distribute IRK
```

The host application in the central device will receive an indication that the remote IRK is distributed. The host must extract the IRK of the remote device (from the *irk* structure in the data union) and store it for use in resolving the peripheral device's random address for reconnection. Below is the sample code:

On the peripheral side, no IRK distribution is requested at the host application layer. The local IRK is stored in BLE stack layers and IRK distribution is handled in the BLE stack.

Since the central device is the distributor of LTK in this example, its host application will receive a GAPC\_BOND\_REQ\_IND message with *request* = GAPC LTK\_EXCH and must distribute the LTK with the corresponding GAPC\_BOND\_CFM message.



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The host application on the peripheral device will receive a GAPC\_BOND\_IND message with *request* = GAPC LTK\_EXCH, containing the distributed LTK. Both devices must store the LTK information for establishing secure links in subsequent connections.

The bonding procedure will be completed by the host applications on both devices by the reception of a GAPC BOND IND message with field *info* = GAPC PAIRING SUCCEED.

Message flow during bonding procedure on both devices is outlined Figure [1].

### 8 Resolving peripheral device random address during scanning

The central host application starts scanning as usual. Upon receiving an advertising report (GAPM\_ADV\_REPORT\_IND) the application checks whether it is from a device with a resolvable random address:

```
int gapm adv report ind handler (ke msg id t msgid,
                                struct gapm adv report ind *param,
                                 ke task id t dest id,
                                ke task id t src id)
{
       if (param->report.adv addr type == 1
              && ( (param->report.adv addr.addr[5] & 0xC0) = 0x40) )
              // it is a resolvable random address
       }
       return (KE MSG CONSUMED);
```

Next, resolve the address by issuing the command GAPM\_RESOLVE\_ADDR\_CMD:

```
struct gapm resolv addr cmd *cmd =
(struct gapm resolv addr cmd *) KE MSG ALLOC DYN (GAPM RESOLVE ADDR CMD, TASK GAPM,
                     TASK APP, gapm resolv addr cmd, N * sizeof(struct gap sec key) );
cmd->operation = GAPM RESOLV ADDR; // GAPM requested operation
                                   // Number of provided IRK
cmd->nb kev = N;
cmd->addr = <<addr>> ; /// Resolvable random address to solve
cmd->irk = <<array of stored IRKs>>; /// Array of IRK used for address resolution (MSB
-> LSB)
/// Resolve Address command
struct gapm resolv addr cmd
   /// GAPM requested operation:
    /// - GAPM RESOLV ADDR: Resolve device address
   uint8 t operation;
    /// Number of provided IRK (sahlle be > 0)
   uint8 t nb key;
    /// Resolvable random address to solve
   struct bd addr addr;
    /// Array of IRK used for address resolution (MSB -> LSB)
   struct gap sec key irk[ ARRAY EMPTY];
};
```

The host application indicates that the address is resolved with a GAPM\_ADDR\_SOLVED\_IND message, containing the resolved address and the IRK resolving it.

```
/// Indicate that resolvable random address has been solved
struct gapm addr solved ind
{
    /// Resolvable random address solved
   struct bd addr addr;
   /// IRK that correctly solved the random address
   struct gap sec key irk;
```

When no provided IRK resolves the address, a GAPM CMP EVT event or GAPM RESOLV ADDR operation with status = GAP ERR NOT FOUND will be sent.



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# 9 Revision history

| Revision | Date        | Description      |
|----------|-------------|------------------|
| 1.0      | 10-Apr-2014 | Initial version. |



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### Status definitions

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|----------------------|--|
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